BONDING THE STARS



Specifications Mechanics

X, Y table

Z-axis Speed

Bond head

Ultrasonic system Wire size Ribbon size

Control

Heating-controller Computer

Monitor Operation system Printer

Work holder Heated work holder Working area 100 x 100 mm Resolution 0.25 μ m, repeatability < 2 μ m 60 mm All axes programmable from 0,2...16 mm/s \leq 30 wires / min.

Wedge-Wedge Thin-Wire (Au/Al) or Ribbon Axis of rotation $\pm 360^{\circ}$

60KHz / 100kHz optional 140KHz 17,5mm up to 75μm 30 μm x 12,5 μm – 250 μm x 25 μm

Integrated in machine 0 - 250 °C optional Single-Board PC, 1,6 GHz Pentium processor, 1 GB RAM, ethernet, USB 4x + 4x frontside TFT flat screen Windows XP All Windows-compatible printers can be installed All bonding parameters can be printed Ø 80mm or optional 4"x4" Ø 80mm and optional 4"x4" (mech. / vacuum) (Attention: 4x4" up to 200°C)



5632DA

Semi-automatic Wedge-Wedge-Bonder

The semi-automatic Wedge-Wedge Bonder 5632 fills the gap between the manual Wedge-Bonders series 53xx and 54xx from F&K Delvotec Semiconductor to the automatic-Bonder from F&K Delvotec.

The 5632 Deep-Access Bonder can be used also as Ribbon-Bonder.

He is on basis 5600-series fully PC controlled and allows any number of bonds to be programmed.

Pre-programmed adjust points are targeted through the camera's cross hair targeting system and the programmed bonds are executed automatically.

Two operating modes are available: Single bond for repair of various bond samples and making single bonds (manualautomatic) and multi wire for teaching and bonding chips or various bond samples (semi and fully automatic).

The 5632 can also be used as Gold Wire, Ball or Alu Heavy Wire Bonder as well as pull-/shear tester by simply replacing the bond head and loading the appropriate software. change over time: approx. 5 minutes.

Ask us for more information !

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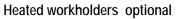
Other features *Programming:*

Automatic bonding of hybrids or COB with programmable X/Y table

Work holders



For components up to 4 x 4" Vacuum and mechanical clamping





For components up to 4 x 4" Vacuum and mechanical clamping Heated

More Work holders available on request.

P

For components up to ø 80 mm Vacuum and mechanical clamping heated

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Head Parking System	For storing of temporary not required bondhead (5610 / 5630 / 5632 / 5650) or pull- and shear-heads. Can be mounted on the left or right side of the machine	
General		
Camera	With cross hair targeting for positioning of bonds / chips	F&K Delvotec Semiconductor GmbH Industriezeile 49a A-5280 Braunau am Inn, Austria Tel.: +43-7722-67052-8270, Fax: +43-7722-67052-8272 Email: info@fkdelvotec.at Internet: www.fkdelvotec.at F&K Delvotec Bondtechnik GmbH & Co.KG 3 International Business Park #04-05 Nordic European Centre
Microscope	Motic (Stereoscope Leica S6, other microscopes optional)	
Lighting	20 W halogen spot light, optional LED direct light	
	Incident light optional	
Dimensions	Height 70 cm, width 70 cm, depth 65 cm; approx. 70 kg	
Supplies	100240 VAC, single-phase, 50/60 Hz, max. 500 VA	
Connections	Air 6 bar, vacuum 0,7 bar ø 6 mm	Singapore 609927 Tel. +65-6890-6020, Fax +65-6890-6021
		F&K Delvotec, Inc.